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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/660,611	09/12/2003	Chun Ho Fan	50626.55	6110

43569 7590 05/12/2006

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EXAMINER	
KEBEDE, BROOK	

ART UNIT	PAPER NUMBER
2823	

DATE MAILED: 05/12/2006

Please find below and/or attached an Office communication concerning this application or proceeding.

Office Action Summary	Application No. 10/660,611	Applicant(s) FAN ET AL.	
	Examiner Brook Kebede	Art Unit 2823	

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

1)☒ Responsive to communication(s) filed on *18 August 2005*.

2a)☒ This action is **FINAL**. 2b)☐ This action is non-final.

3)☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

4)☒ Claim(s) *13,15-1-23, 25 and 26* is/are pending in the application.

4a) Of the above claim(s) *18,19 and 26* is/are withdrawn from consideration.

5)☐ Claim(s) _____ is/are allowed.

6)☐ Claim(s) *13,15-17,20-23 and 25* is/are rejected.

7)☐ Claim(s) _____ is/are objected to.

8)☐ Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

9)☐ The specification is objected to by the Examiner.

10)☒ The drawing(s) filed on *18 August 2005* is/are: a)☒ accepted or b)☐ objected to by the Examiner.

Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).

Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).

11)☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

12)☐ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).

a)☐ All b)☐ Some * c)☐ None of:

1.☐ Certified copies of the priority documents have been received.

2.☐ Certified copies of the priority documents have been received in Application No. _____.

3.☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

* See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

1) ☒ Notice of References Cited (PTO-892)
2) ☐ Notice of Draftsperson's Patent Drawing Review (PTO-948)
3) ☐ Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08) Paper No(s)/Mail Date _____.
4) ☐ Interview Summary (PTO-413) Paper No(s)/Mail Date. _____.
5) ☐ Notice of Informal Patent Application (PTO-152)
6) ☐ Other: _____.

DETAILED ACTION

Election/Restrictions

1. Applicants' election without traverse of Species I, i.e., claims 13, 15-17, 20-23 and 25, in the reply filed on February 21, 2006 is acknowledged.

2. Accordingly, claims 18, 19 and 26 are withdrawn from further consideration pursuant to 37 CFR 1.142(b) as being drawn to a nonelected species, there being no allowable generic or linking claim. Election was made **without** traverse in the reply filed on February 21, 2006.

Status of the Claim

3. Claims 13, 15-25 and 26 are pending in the application.

4. Claims 18, 19 and 26 are withdrawn form consideration as set forth in Paragraph 2 above.

5. Claims 13, 15-17, 20-23 and 25 are treated on the merit as set forth herein below.

Drawings

6. The drawings were received on August 18, 2005. These drawings are acceptable.

Claim Rejections - 35 USC § 102

7. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

> A person shall be entitled to a patent unless -
>
> (b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

8. Claims 13, 15- 17, 20-22 and 25 are rejected under 35 U.S.C. 102(b) as being anticipated by Huang et al. (US/2002/0113308).

Re claim 13, Huang et al. disclose an integrated circuit package comprising: a substrate (20) having a plurality of conductive traces (22) (i.e., i.e., plurality of gold wires **22** which

commonly known as **a conductive trace** in the art) (see Fig. 1); a plurality of balls (230) (i.e., the solder balls **230**) disposed on a first surface of the substrate (20) (see Fig. 1); a semiconductor die (21) (i.e., the semiconductor chip **21** and also known as semiconductor die) mounted to the substrate (20) such that bumps (230) of the semiconductor die (21) are electrically connected to conductive traces of the substrate (see Fig. 1); an overmold material encapsulating (25) (i.e., encapsulant **25**) the semiconductor die (21) and the balls (230) that are disposed farthest form the substrate (20) are exposed (see Fig. 1) at and exterior of the IC package (see Fig. 1); and a ball grid array (24) disposed on a second surface (i.e., bottom surface) of the substrate (20) and in electrical connection with the conductive traces (See Figs. 1 and 5-6 and related text in Paragraphs [0023] through Paragraph [0046]).

Re claim 15, as applied to claim 13 above, Huang et al. disclose all the claimed limitations including the limitation wherein the plurality of balls (230) is attached to respective solder ball pads (see Abstract) on the first surface of the substrate (i.e., top surface) (20) (See Figs. 1 and 5-6 and related text in Paragraphs [0023] through Paragraph [0046]).

Re claim 16, as applied to claim 13 above, Huang et al. disclose all the claimed limitations including the limitation wherein the bumps (i.e., the ball grid array **24**) of the semiconductor die (21) are electrically connected to the conductive traces (22) by wire bonds (See Figs. 1 and 5-6 and related text in Paragraphs [0023] through Paragraph [0046]).

Re claim 17, as applied to claim 13 above, Huang et al. disclose all the claimed limitations including the limitation wherein the semiconductor die is fixed to the first surface of the substrate (See Figs. 1 and 5-6 and related text in Paragraphs [0023] through Paragraph [0046]).

Re claim 20, as applied to claim 13 above, Huang et al. disclose all the claimed limitations including the limitation wherein the plurality of balls circumscribe the semiconductor die (See Figs. 1 and 5-6 and related text in Paragraphs [0023] through Paragraph [0046]).

Re claim 21, as applied to claim 13 above, Huang et al. disclose all the claimed limitations including the limitation wherein the plurality of balls electrically connected to the conductive traces of the substrate (See Figs. 1 and 5-6 and related text in Paragraphs [0023] through Paragraph [0046]).

Re claim 22, as applied to claim 13 above, Huang et al. disclose all the claimed limitations including the limitation wherein the balls are deformed (i.e., the solder balls 230 are formed by reflow that requires deformation process) (See Figs. 1 and 5-6 and related text in Paragraphs [0023] through Paragraph [0046]).

Re claim 24, as applied to claim 13 above, Huang et al. disclose all the claimed limitations including the limitation further comprising a heat spreader (231) mounted to the balls (See Figs. 1 and 5-6 and related text in Paragraphs [0023] through Paragraph [0046]).

Re claim 25, as applied to claim 13 above, Huang et al. disclose all the claimed limitations including the limitation wherein the plurality of balls is comprised of a plurality of solder balls (See Figs. 1 and 5-6 and related text in Paragraphs [0023] through Paragraph [0046]).

Claim Rejections - 35 USC § 103

9. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

> (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person

having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

This application currently names joint inventors. In considering patentability of the claims under 35 U.S.C. 103(a), the examiner presumes that the subject matter of the various claims was commonly owned at the time any inventions covered therein were made absent any evidence to the contrary. Applicant is advised of the obligation under 37 CFR 1.56 to point out the inventor and invention dates of each claim that was not commonly owned at the time a later invention was made in order for the examiner to consider the applicability of 35 U.S.C. 103(c) and potential 35 U.S.C. 102(e), (f) or (g) prior art under 35 U.S.C. 103(a).

10. Claim 23 is rejected under 35 U.S.C. 103(a) as being unpatentable over Huang et al. (US/2002/0113308), as applied in Paragraph 6 above, in view of Huang et al. (US/6,707,167).

Re claim 23, Huang et al. disclose all the claimed limitations except a die adapter mounted on said semiconductor die and encapsulated in the overmold material.

Huang et al. '167 disclose an IC package that a die adopter (16) that is mounted on the semiconductor die (12) which encapsulated in the overmold material (14) (see Fig. 2). As Huang et al. '167 disclose the die adopter 16 prevents cracking of the IC die (see Col. 3, lines 38-55).

Therefore, it would have been obvious to one having ordinary skill in the art at the time of applicant(s) claimed invention was made to provide Huang et al. '0113308 reference with die adopter as taught by Huang et al. '167 in order to prevent die cracking.

Response to Arguments

11. Applicants' arguments filed on August 18, 205 have been fully considered but they are not persuasive.

Applicants argue that "Huang et al. certainly fails to teach or suggest the feature of *an overmold material encapsulating said semiconductor die and said balls on said substrate such that portions of said balls that are disposed farthest from said substrate are exposed at an exterior of said Integrated circuit package...*"

In response to applicants' contention, it is respectfully submitted that Huang et al. '0113308 disclose all the claimed limitations including "overmold material encapsulating said semiconductor die and said balls on said substrate such that portions of said balls that are disposed farthest from said substrate are exposed at an exterior of said Integrated circuit package," as depicted in Fig. 1.

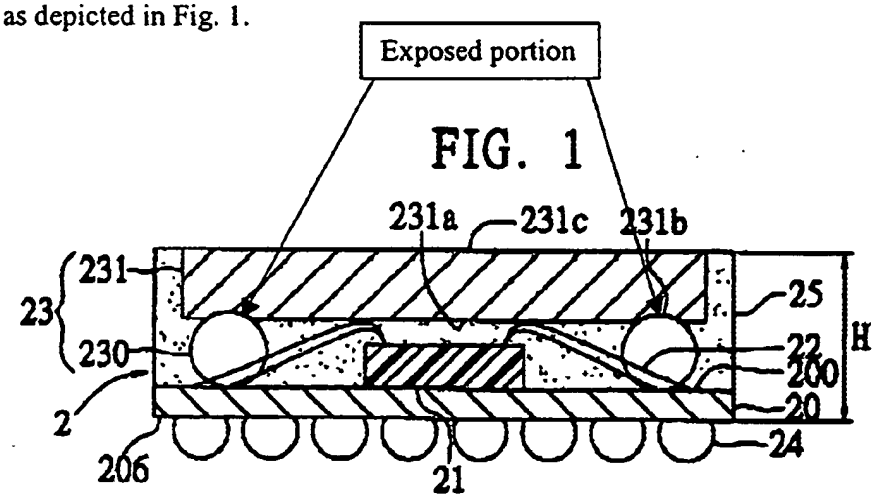

FIG. 1

As shown above, the exposed portion of the balls **230** is at exterior portion of the package which is farthest form the substrate **20**. In addition the heat sink **231** is in contact with the exposed portion of balls **230** and the overmold material **25** also encapsulating the semiconductor die **21** and the balls **230**. Furthermore, the semiconductor die **21** is electrically connected to solder balls **24** for external connection via through conductive traces **22** (see Page 2, Paragraph 0024).

Therefore, the rejection of claims 13, 15- 17, 20-22, 24 and 25 under 35 U.S.C. § 102(b) is deemed proper. In addition, the rejection of claim 23 under 35 U.S.C. § 103(a) is deemed proper and the *prima facie* case of obviousness has been met.

Conclusion

12. Applicants' amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL.** See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

Correspondence

13. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Brook Kebede whose telephone number is (571) 272-1862. The examiner can normally be reached on 8-5 Monday to Friday.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Matthew S. Smith can be reached on (571) 272-1907. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Brook Kebede

Brook Kebede
Primary Examiner
Art Unit 2823

BK
May 10, 2006